

Title (en)  
ELECTRONIC COMPONENT COMPRISING A SEMICONDUCTOR CHIP AND A PLASTIC HOUSING, AND METHOD FOR PRODUCING THE SAME

Title (de)  
ELEKTRONISCHES BAUTEIL MIT HALBLEITERCHIP UND KUNSTSTOFFGEHÄUSE UND VERFAHREN ZUR HERSTELLUNG DESSELBEN

Title (fr)  
COMPOSANT ELECTRONIQUE COMPRENANT UNE PUCE SEMI-CONDUCTRICE ET UN BOITIER EN PLASTIQUE ET SON PROCEDE DE PRODUCTION

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Application  
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Abstract (en)  
[origin: WO2004082018A2] The invention relates to an electronic component comprising a semiconductor chip (1). Said semiconductor chip (1) is contained in a plastic housing (6) in such a way that the rear side (3) and the lateral sides (4, 5) thereof are embedded in a plastic material (7). The lateral sides (4, 5) and/or the rear side (3) of the semiconductor chip (2) have an anchoring region (10) which enables the semiconductor chip (1) to positively engage with the surrounding plastic material (7). The invention also relates to a method for producing the inventive component.

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